SPECIFICATION

CUSTOMER : _____

MODULE NO.: AGM-12864E1-201

APPROVED BY: (FOR CUSTOMER USE ONLY)	PCB VERSION: DATA:

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

VERSION	DATE	REVISED PAGE NO.	SUMMARY
G	2019/12/17		Modify Precautions in use of LCD Modules

MODLE NO：
AGM-12864E1-201

RECORDS OF REVISION			DOC. FIRST ISSUE
VERSION	DATE	REVISED PAGE NO.	SUMMARY
0	2009/04/22		First issue
A	2010/09/02		Correct VLED
B	2013/09/29		Remove IC information
C	2015/08/07		Modify frame=54.2*40.7mm
D	2016/01/27		Modify Precautions in use of LCD Modules & Static electricity test
E	2017/08/30		Modify B/L information
F	2019/08/27		Modify Material List of Components for RoHs
G	2019/12/17		Modify Precautions in use of LCD Modules

Contents

1.Precautions in use of LCD Modules

(1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.

(2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.

(3) Don't disassemble the LCM.

(4) Don't operate it above the absolute maximum rating.

(5)Don't drop, bend or twist LCM.

(6) Soldering: only to the I/O terminals.

(7) Storage: please storage in anti-static electricity container and clean environment.

(8) AGT have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors,capacitors and other passive components will have different appearance and color caused by the different supplier.)

(9) have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, have the right to modify the version.)

(10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.

(11)Please heat up a little the tape sticking on the components when removing it; otherwise the components might be damaged.

2.General Specification

Item	Dimension	Unit
Number of dots	128 x 64	—
Module dimension	55.0 x 50.0 x 10.0 (MAX)	mm
View area	43.5 x 29.0	mm
Active area	40.92 x 26.92	mm
Dot size	0.28 x 0.35	mm
Dot pitch	0.32 x 0.39	mm
LCD type	STN Positive, Yellow Green Transflective (In LCD production, It will occur slightly color difference. We can only guarantee the same color in the same batch.)	
Duty	1/64	
View direction	6 o'clock	
Backlight Type	LED, Yellow Green	
IC	NT7107,NT7108	

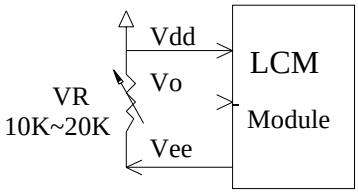
3.Absolute Maximum Ratings

Item	Symbol	Min	Typ	Max	Unit
Operating Temperature	T_{OP}	-20	—	+70	℃
Storage Temperature	T_{ST}	-30	—	+80	℃
Supply Voltage For Logic	V_{DD}-V_{SS}	-0.3	—	7.0	V
Driver Supply Voltage	V_{LCD}	V_{EE}-0.3	—	V_{DD}+0.3	V

4.Electrical Characteristics

ITEM	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT
Supply Voltage For Logic	V_{DD}-V_{SS}	—	4.5	5.0	5.5	V
Supply Voltage For LCD *Note	V_{DD}-V_O	Ta=-20℃ Ta=25℃ Ta=70℃	— 8.4 7.0	— 8.6 —	9.8 8.8 —	V V V
Input High Volt.	V_{IH}	—	0.7 V_{DD}	—	V_{DD}	V
Input Low Volt.	V_{IL}	—	0	—	0.8	V
Output High Volt.	V_{OH}	—	2.4	—	—	V
Output Low Volt.	V_{OL}	—	—	—	0.4	V
Supply Current	I_{DD}	V_{DD}=5.0V	1.0	1.2	1.5	mA

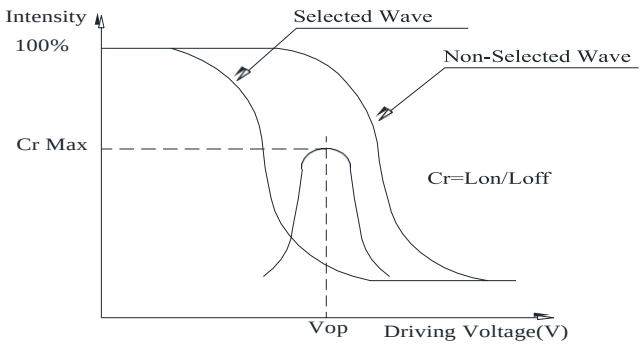
* Note: Please design the VOP adjustment circuit on customer's main board

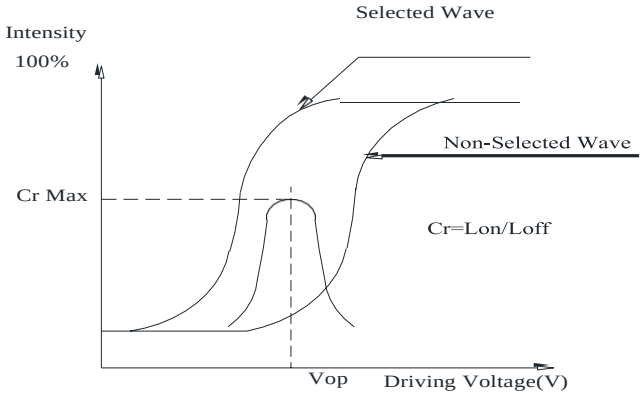


5.Optical Characteristics

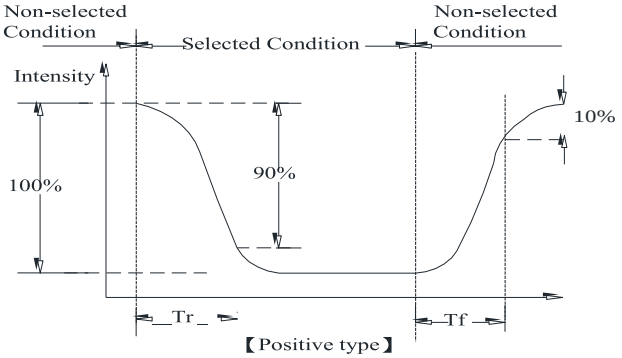
Item	Symbol	Condition	Min	Typ	Max	Unit
View Angle	θ	CR≧2	0	—	20	ψ = 180°
	θ	CR≧2	0	—	40	ψ = 0°
	θ	CR≧2	0	—	30	ψ = 90°
	θ	CR≧2	0	—	30	ψ = 270°
Contrast Ratio	CR	—	—	3	—	—
Response Time	T rise	—	—	200	300	ms
	T fall	—	—	250	350	ms

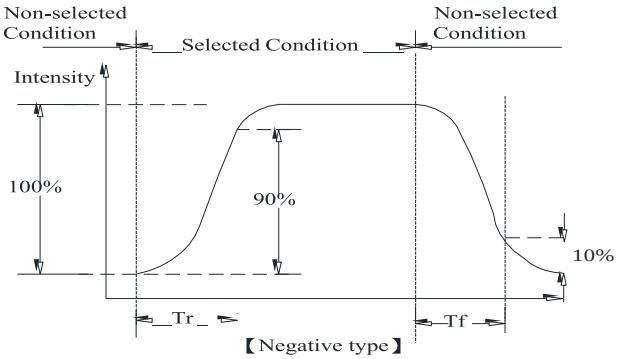
Definition of Operation Voltage (Vop)





Definition of Response Time (Tr , Tf)

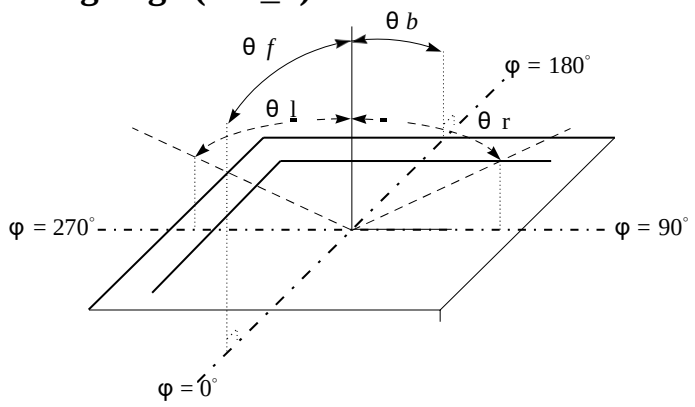




Conditions :

Operating Voltage : Vop　　Viewing Angle(θ ，φ) : 0°， 0°
Frame Frequency : 64 HZ　　Driving Waveform : 1/N duty , 1/a bias

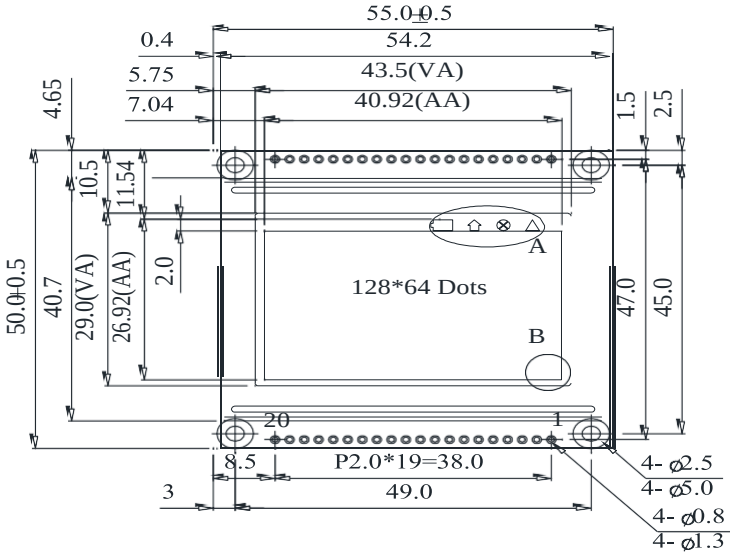
Definition of viewing angle(CR≧2)

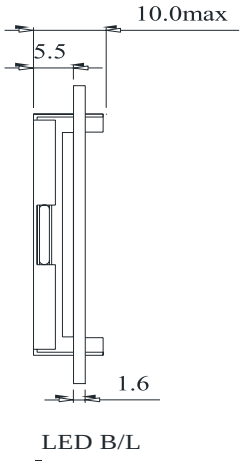


6.Interface Pin Function

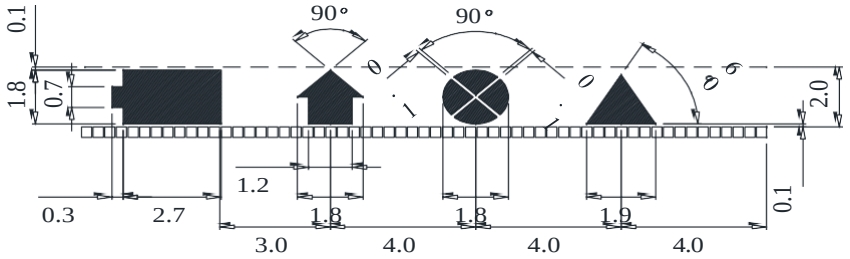
Pin No.	Symbol	Level	Description
1	Vss	0V	Ground
2	V_{dd}	5.0V	Supply voltage for logic
3	V_O	(Variable)	Operating voltage for LCD
4	D/I	H/L	H: Data , L: Instruction
5	R/W	H/L	H: Read(MPU←Module) , L :Write(MPU→Module)
6	E	H	Enable signal
7	DB0	H/L	Data bus line
8	DB1	H/L	Data bus line
9	DB2	H/L	Data bus line
10	DB3	H/L	Data bus line
11	DB4	H/L	Data bus line
12	DB5	H/L	Data bus line
13	DB6	H/L	Data bus line
14	DB7	H/L	Data bus line
15	CS1	H	Chip Enable (Select Column 1 ~ Column 64)
16	CS2	H	Chip Enable (Select Column 65 ~ Column 128)
17	/RST	L	Reset signal
18	V_{EE}		Negative Voltage output
19	A	—	Power supply for B/L(+)
20	K	—	Power supply for B/L(-)

7.Contour Drawing &Block Diagram

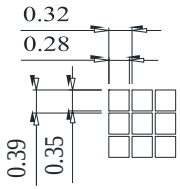




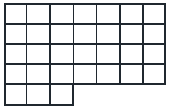
PIN NO.	SYMBOL
1	Vss
2	Vdd
3	Vo
4	D/I
5	R/W
6	E
7	DB0
8	DB1
9	DB2
10	DB3
11	DB4
12	DB5
13	DB6
14	DB7
15	CS1
16	CS2
17	RST
18	Vee
19	A
20	K



DETAIL A
SCALE 5/1

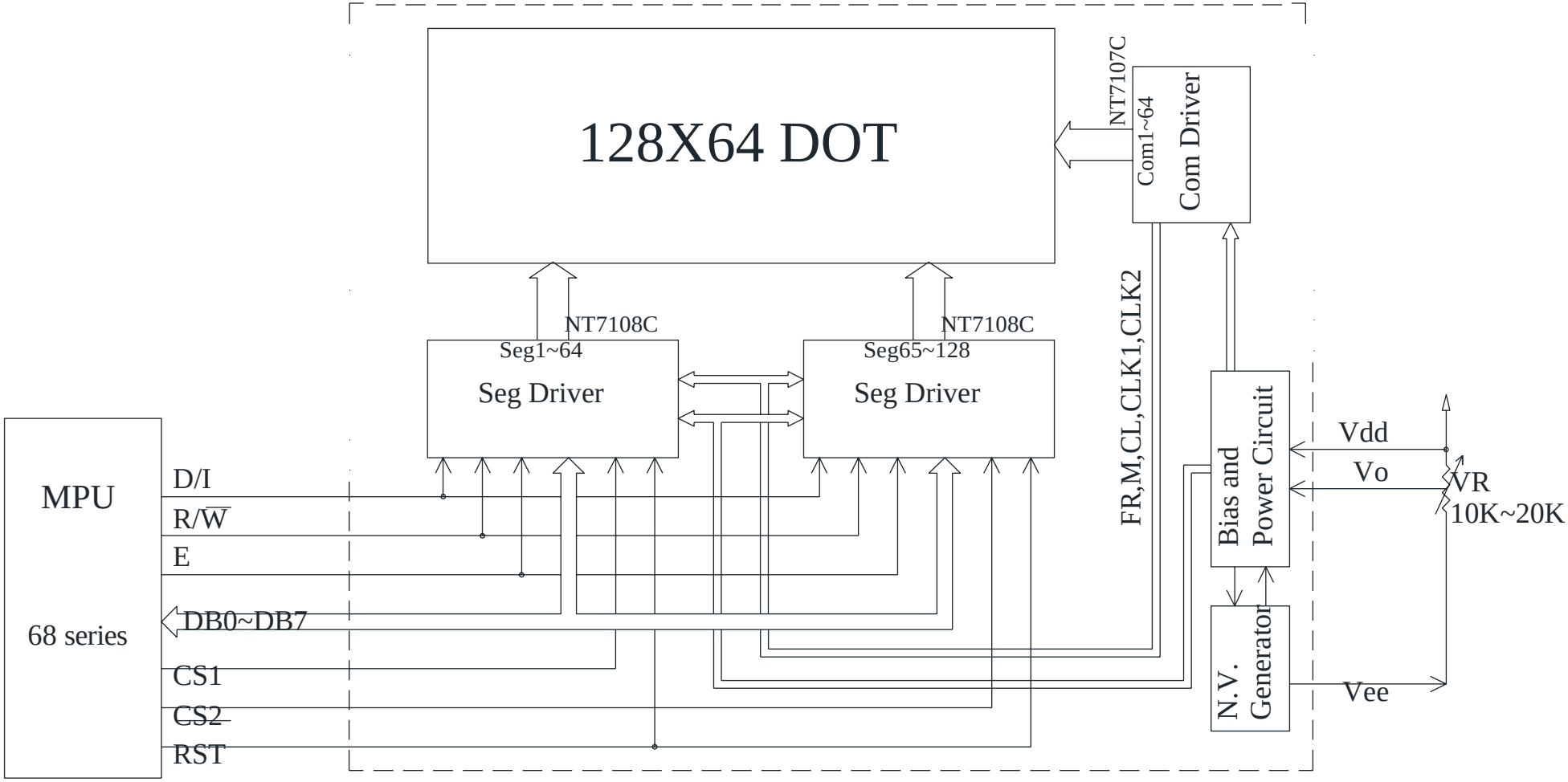


DOT SIZE
SCALE 10/1



The non-specified tolerance of dimension is ±0.3 mm .

DETAIL B
SCALE 10/1



External contrast adjustment.

8.Reliability

Content of Reliability Test (Wide temperature, -20℃~70℃)

Environmental Test			
Test Item	**Content of Test**	**Test Condition**	**Note**
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80℃ 200hrs	2
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30℃ 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70℃ 200hrs	— —
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20℃ 200hrs	1
High Temperature/ Humidity storage	The module should be allowed to stand at 60 ℃,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60℃,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20℃ 25℃ 70℃ 30min 5min 30min 1 cycle	-20℃/70℃ 10 cycles	— —
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude : 1.5mm Vibration Frequency : 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact), ±800v(air), RS=330Ω CS=150pF 10 times	— —

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

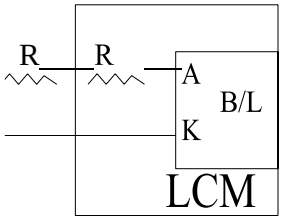
9.Backlight Information

Specification

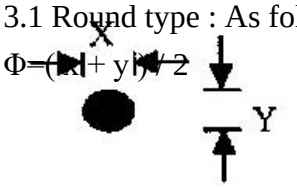
PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	-	64	80	mA	-
Supply Voltage	V	4.9	5.0	5.1	V	ILED=64mA
Reverse Voltage	VR	-	-	5	V	-
Wavelength	λ D	569	-	575		ILED=64mA
Luminance (Without LCD)	IV	32	40	-	CD/M^2	ILED=64mA
Life Time	-	-	50000	-	Hr.	ILED≦64mA 25℃,50-60%RH
Color	Yellow Green					

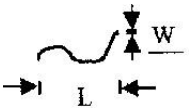
Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

2.Drive from pin19,pin20



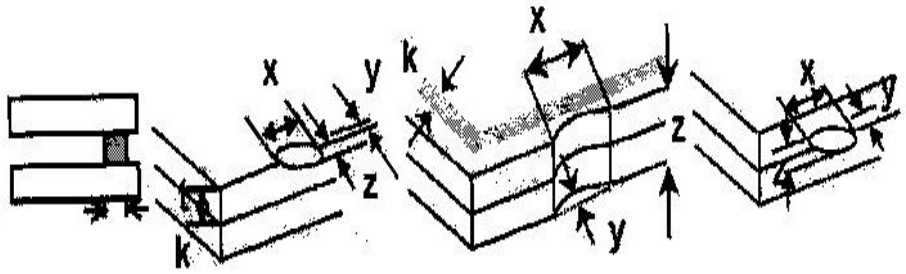
10.Inspection specification

<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>01</td><td>Electrical Testing</td><td>Missing vertical, horizontal segment, segment contrast defect.
Missing character , dot or icon.
Display malfunction.
No function or no display.
Current consumption exceeds product specifications.
LCD viewing angle defect.
Mixed product types.
Contrast defect.</td><td>0.65</td></tr>
<tr><td>02</td><td>Black or white spots on LCD (display only)</td><td>2.1 White and black spots on display ≦0.25mm, no more than three white or black spots present.
2.2 Densely spaced: No more than two spots or lines within 3mm</td><td>2.5</td></tr>
<tr><td rowspan="2">03</td><td rowspan="2">LCD black spots, white spots, contamination (non-display)</td><td>3.1 Round type : As following drawing
Φ=(x+ y)/2
 

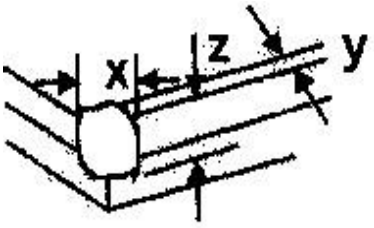
<table><tr><td>SIZE</td><td>Acceptable Q TY</td></tr><tr><td>Φ≦0.10</td><td>Accept no dense</td></tr><tr><td>0.10＜Φ≦0.20</td><td>2</td></tr><tr><td>0.20＜Φ≦0.25</td><td>1</td></tr><tr><td>0.25＜Φ</td><td>0</td></tr></table></td><td>2.5</td></tr>
<tr><td>3.2 Line type : (As following drawing)
 

<table><tr><td>Length</td><td>Width</td><td>Acceptable Q TY</td></tr><tr><td>---</td><td>W≦0.02</td><td>Accept no dense</td></tr><tr><td>L≦3.0</td><td>0.02＜W≦0.03</td><td rowspan="2">2</td></tr><tr><td>L≦2.5</td><td>0.03＜W≦0.05</td></tr><tr><td>---</td><td>0.05＜W</td><td>As round type</td></tr></table></td><td>2.5</td></tr>
<tr><td>04</td><td>Polarizer bubbles</td><td>If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.
<table><tr><td>Size Φ</td><td>Acceptable Q TY</td></tr><tr><td>Φ≦0.20</td><td>Accept no dense</td></tr><tr><td>0.20＜Φ≦0.50</td><td>3</td></tr><tr><td>0.50＜Φ≦1.00</td><td>2</td></tr><tr><td>1.00＜Φ</td><td>0</td></tr><tr><td>Total Q TY</td><td>3</td></tr></table></td><td>2.5</td></tr>
</table>

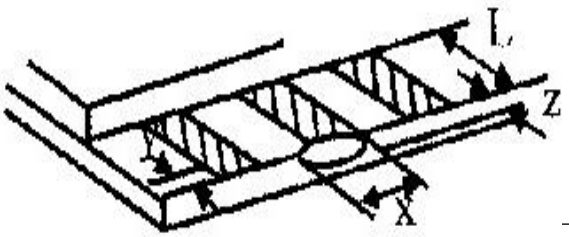
<table>
<tr><td>NO</td><td>Item</td><td>Criterion</td><td>AQL</td></tr>
<tr><td>05</td><td>Scratches</td><td>Follow NO.3 LCD black spots, white spots, contamination</td><td></td></tr>
<tr><td>06</td><td>Chipped glass</td><td>Symbols Define:
x: Chip length y: Chip width z: Chip thickness
k: Seal width t: Glass thickness a: LCD side length
L: Electrode pad length:

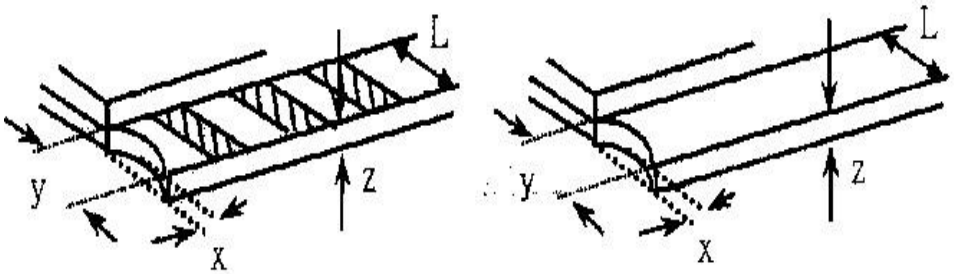
6.1 General glass chip :
6.1.1 Chip on panel surface and crack between panels:
 

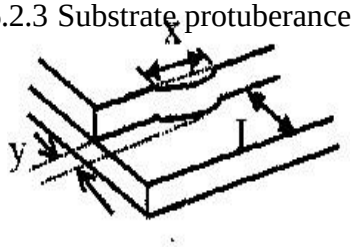
<table><tr><td></td><td></td><td></td></tr><tr><td>z: Chip thickness
Z≦1/2t</td><td>y: Chip width
Not over viewing area</td><td>x: Chip length
x≦1/8a</td></tr><tr><td>1/2t＜z≦2t</td><td>Not exceed 1/3k</td><td>x≦1/8a</td></tr></table>⊙If there are 2 or more chips, x is total length of each chip.

6.1.2 Corner crack:
 

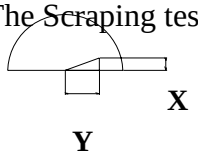
<table><tr><td></td><td></td><td></td></tr><tr><td>z: Chip thickness
Z≦1/2t</td><td>y: Chip width
Not over viewing area</td><td>x: Chip length
x≦1/8a</td></tr><tr><td>1/2t＜z≦2t</td><td>Not exceed 1/3k</td><td>x≦1/8a</td></tr></table>⊙If there are 2 or more chips, x is the total length of each chip.</td><td>2.5</td></tr>
</table>

<table>
<tr><th>NO</th><th>Item</th><th>Criterion</th><th>AQL</th></tr>
<tr><td>06</td><td>Glass crack</td><td>
Symbols :
x: Chip length y: Chip width z: Chip thickness
k: Seal width t: Glass thickness a: LCD side length
L: Electrode pad length
6.2 Protrusion over terminal :
6.2.1 Chip on electrode pad :


<table>
<tr><td></td><td></td><td></td></tr>
<tr><td>y: Chip width
y≦0.5mm</td><td>x: Chip length
x≦1/8a</td><td>z: Chip thickness
0 ＜ z ≦ t</td></tr>
</table>
6.2.2 Non-conductive portion:


<table>
<tr><td></td><td></td><td></td></tr>
<tr><td>y: Chip width
y≦ L</td><td>x: Chip length
x≦1/8a</td><td>z: Chip thickness
0 ＜ z ≦ t</td></tr>
</table>
⊙If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.
⊙If the product will be heat sealed by the customer, the alignment mark not be damaged.
6.2.3 Substrate protuberance and internal crack.


<table>
<tr><td></td><td></td></tr>
<tr><td>y: width
y≦1/3L</td><td>x: length
x ≦ a</td></tr>
</table>
</td><td>2.5</td></tr>
</table>

NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong.	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB、COB	10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB  X * Y<=2mm^2	2.5 2.5 0.65 2.5 2.5 0.65 0.65 2.5 2.5
11	Soldering	11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB.	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
12	General appearance	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever.	2.5
		12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.	2.5
		12.7 Sealant on top of the ITO circuit has not hardened.	2.5
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging specification sheet.	0.65
		12.11 Product dimension and structure must conform to product specification sheet.	0.65
		12.12 Visual defect outside of VA is not considered to be rejection.	0.65

11.Material List of Components for RoHs

1. Display Co., Ltd hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

   Exhibit A：The Harmful Material List

Material	Cd	Pb	Hg	Cr6+	PBB	PBDE	DEHP	BBP	DBP	DIBP
Limited Value	**100 ppm**	**1000 ppm**	**1000 ppm**	**1000 ppm**	**1000 ppm**	**1000 ppm**	**1000 ppm**	**1000 ppm**	**1000 ppm**	**1000 ppm**
Above limited value is set up according to RoHS.										

2.Process for RoHS requirement：**(only for RoHS inspection)**

(1) Use the Sn/Ag/Cu soldering surface；the surface of Pb-free solder is rougher than we used before.

(2) Heat-resistance temp.： Reflow：

250℃,30 seconds Max.；

Connector soldering wave or hand soldering：320℃, 10 seconds max.

(3) Temp. curve of reflow, max. Temp.：235±5℃ ；

Recommended customer's soldering temp. of connector：280℃, 3 seconds.

12.Recommendable Storage

1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
2. Do not place the module near organics solvents or corrosive gases.
3. Do not crush, shake, or jolt the module.

1、**Panel Specification**：

1. Panel Type： ☐ Pass ☐ NG ,_____
2. View Direction： ☐ Pass ☐ NG ,_____
3. Numbers of Dots： ☐ Pass ☐ NG ,_____
4. View Area： ☐ Pass ☐ NG ,_____
5. Active Area： ☐ Pass ☐ NG ,_____
6. Operating Temperature： ☐ Pass ☐ NG ,_____
7. Storage Temperature： ☐ Pass ☐ NG ,_____
8. Others：_____

2、**Mechanical Specification**：

1. PCB Size： ☐ Pass ☐ NG ,_____
2. Frame Size： ☐ Pass ☐ NG ,_____
3. Materal of Frame： ☐ Pass ☐ NG ,_____
4. Connector Position： ☐ Pass ☐ NG ,_____
5. Fix Hole Position： ☐ Pass ☐ NG ,_____
6. Backlight Position： ☐ Pass ☐ NG ,_____
7. Thickness of PCB： ☐ Pass ☐ NG ,_____
8. Height of Frame to PCB： ☐ Pass ☐ NG ,_____
9. Height of Module： ☐ Pass ☐ NG ,_____
10. Others： ☐ Pass ☐ NG ,_____

3、**Relative Hole Size**：

1. Pitch of Connector： ☐ Pass ☐ NG ,_____
2. Hole size of Connector： ☐ Pass ☐ NG ,_____
3. Mounting Hole size： ☐ Pass ☐ NG ,_____
4. Mounting Hole Type： ☐ Pass ☐ NG ,_____
5. Others： ☐ Pass ☐ NG ,_____

4、**Backlight Specification**：

1. B/L Type： ☐ Pass ☐ NG ,_____
2. B/L Color： ☐ Pass ☐ NG ,_____
3. B/L Driving Voltage (Reference for LED Type)： ☐ Pass ☐ NG ,__
4. B/L Driving Current： ☐ Pass ☐ NG ,_____
5. Brightness of B/L： ☐ Pass ☐ NG ,_____
6. B/L Solder Method： ☐ Pass ☐ NG ,_____
7. Others： ☐ Pass ☐ NG ,_____

5、Electronic Characteristics of Module：

1.	Input Voltage：	☐ Pass	☐ NG ,__
2.	Supply Current：	☐ Pass	☐ NG ,__
3.	Driving Voltage for LCD：	☐ Pass	☐ NG ,__
4.	Contrast for LCD：	☐ Pass	☐ NG ,__
5.	B/L Driving Method：	☐ Pass	☐ NG ,__
6.	Negative Voltage Output：	☐ Pass	☐ NG ,__
7.	Interface Function：	☐ Pass	☐ NG ,__
8.	LCD Uniformity：	☐ Pass	☐ NG ,__
9.	ESD test：	☐ Pass	☐ NG ,__
10.	Others：	☐ Pass	☐ NG ,__

6、Summary：

Sales signature：_____

Customer Signature：_____ **Date：** / /